

Technical Data Sheet

Schulamid 66 MV 2 BLK 968001

Polyamide 66

Product Description

Medium viscosity Polyamide 66 - standard grade

Processing Method Injection Molding

Attribute Good Surface Finish; Medium Viscosity; Oil Resistant

Typical Properties	Nominal Value	Units	Test Method
Physical			
Density, (Method A)	1.14	g/cm ³	ISO 1183
Viscosity Number	140	cm ³ /g	ISO 307
Mechanical			
Tensile Stress at Yield			
(Type 1A, 50 mm/min)	85.0	MPa	ISO 527-2
(Type 1A, 50 mm/min) - Conditioned	55.0	MPa	ISO 527-2
Tensile Strain at Yield			
(Type 1A, 50 mm/min)	5.0	%	ISO 527-2
(Type 1A, 50 mm/min) - Conditioned	20	%	ISO 527-2
Tensile Modulus			
(1 mm/min, Type 1A)	3200	MPa	ISO 527-1
(1 mm/min, Type 1A) - Conditioned	1300	MPa	ISO 527-1
Impact			
Charpy Impact Strength - Notched			
(23 °C, Type 1, Edgewise, Notch A)	6.0	kJ/m ²	ISO 179
(-30 °C, Type 1, Edgewise, Notch A)	4.0	kJ/m ²	ISO 179
(23 °C, Type 1, Edgewise, Notch A) - Conditioned	12	kJ/m ²	ISO 179
Charpy Impact Strength - Unnotched			
(23 °C, Type 1, Edgewise)	No Break		ISO 179
(-30 °C, Type 1, Edgewise)	No Break		ISO 179
(23 °C, Type 1, Edgewise) - Conditioned	No Break		ISO 179
Thermal			
Vicat Softening Temperature			
(B (50N), 50 °C/h)	240	°C	ISO 306
(A (10N), 50 °C/h)	245	°C	ISO 306
Deflection Temperature Under Load Unannealed (0.45 MPa), (Flatwise)	220	°C	ISO 75-2/B
Deflection Temperature Under Load Unannealed (1.80 MPa), (Flatwise)	80.0	°C	ISO 75-2/A
Electrical			

Volume Resistivity	>1.0E+13	ohm*m	IEC 62631-3-1
- Conditioned	>1.0E+10	ohm*m	IEC 62631-3-1
Surface Resistivity	>1.0E+15	ohm	IEC 60093
- Conditioned	>1.0E+12	ohm	IEC 60093

Flammable

Burning Rate			
(2.00 mm)	0.0	mm/min	FMVSS 302
(2.00 mm)	0.0	mm/min	ISO 3795
Glow Wire Flammability Index			
(1.5 mm)	850	°C	IEC 60695-2-12
(3.0 mm)	850	°C	IEC 60695-2-12

UL Information

Flammability Classification			
(1.5 mm)	V-2		IEC 60695-11-10, -20
(3.0 mm)	V-2		IEC 60695-11-10, -20
UL File Number	E86615		

Injection Parameters	Nominal	
	Value	Units
Drying Time	3.0 to 4.0	hr
Drying Temperature	80	°C
Suggested Max Moisture	0.040 to 0.10	%
Processing (Melt) Temp	270 to 290	°C
Mold Temperature	60 to 100	°C